

Specification for Approval

PRODUCT NAME: RGS10128032WR006
PRODUCT NO.: 9923601000

CUSTOMER
APPROVED BY
DATE:

RITDISPLAY CORP. APPROVED

REVISION RECORD

REV.	REVISION DESCRIPTION	REV. DATE	REMARK
X01	INITIAL RELEASE	2008. 12. 22	
X02	<ul style="list-style-type: none"> ■ Add the operating conditions for different luminance ■ Modify the D.C electrical characteristics ■ Add the panel electrical specifications ■ Add the application circuit 	2009. 02. 25	Page 6, 7, 8, 9 & 16
A01	<ul style="list-style-type: none"> ■ Transfer from X version ■ Modify definition of panel thickness ■ Add the information of module weight ■ Add the packing specification 	2009. 05. 13	Page 5 & 19

CONTENTS

ITEM	PAGE
<u>1. SCOPE</u>	4
<u>2. WARRANTY</u>	4
<u>3. FEATURES</u>	4
<u>4. MECHANICAL DATA</u>	5
<u>5. MAXIMUM RATINGS</u>	6
<u>6. ELECTRICAL CHARACTERISTICS</u>	7
6.1 D.C ELECTRICAL CHARACTERISTICS	
6.2 ELECTRO-OPTICAL CHARACTERISTICS	
<u>7. INTERFACE</u>	10
7.1 FUNCTION BLOCK DIAGRAM	
7.2 PANEL LAYOUT DIAGRAM	
7.3 PIN ASSIGNMENTS	
7.4 GRAPHIC DISPLAY DATA RAM ADDRESS MAP	
7.5 INTERFACE TIMING CHART	
<u>8. POWER ON / OFF SEQUENCE & APPLICATION CIRCUIT</u>	15
8.1 POWER ON / OFF SEQUENCE	
8.2 APPLICATION CIRCUIT	
8.3 COMMAND TABLE	
<u>9. RELIABILITY TEST CONDITIONS</u>	17
<u>10. EXTERNAL DIMENSION</u>	18
<u>11. PACKING SPECIFICATION</u>	19
<u>12. APPENDIXES</u>	20

1. SCOPE

The purpose of this specification is to define the general provisions and quality requirements that apply to the supply of display cells manufactured by RiTdisplay. This document, together with the Module Assembly Drawing, is the highest-level specification for this product. It describes the product, identifies supporting documents and contains specifications.

2. WARRANTY

RiTdisplay warrants that the products delivered pursuant to this specification (or order) will conform to the agreed specifications for twelve (12) months from the shipping date ("Warranty Period"). RiTdisplay is obligated to repair or replace the products which are found to be defective or inconsistent with the specifications during the Warranty Period without charge, on condition that the products are stored or used as the conditions specified in the specifications. Nevertheless, RiTdisplay is not obligated to repair or replace the products without charge if the defects or inconsistency are caused by the force majeure or the reckless behaviors of the customer.

After the Warranty Period, all repairs or replacements of the products are subject to charge.

3. FEATURES

- Small molecular organic light emitting diode.
- Color : White
- Panel matrix : 128*32
- Driver IC : LD7032
- Excellent quick response time.
- Extremely thin thickness for best mechanism design : 1.21mm
- High contrast : 2000:1
- Wide viewing angle : 160°
- 8080 or 6800 series parallel interface, Serial Peripheral Interface, I²C Serial Interface.
- Wide range of operating temperature : -40 to 70 °C
- Anti-glare polarizer.

4. MECHANICAL DATA

NO	ITEM	SPECIFICATION	UNIT
1	Dot Matrix	128 (W) x 32 (H)	dot
2	Dot Size	0.18 (W) x 0.18 (H)	mm ²
3	Dot Pitch	0.20 (W) x 0.20 (H)	mm ²
4	Aperture Rate	81	%
5	Active Area	25.58 (W) x 6.38 (H)	mm ²
6	Panel Size	29.8 (W) x 15.4 (H)	mm ²
7*	Panel Thickness	1.02 ± 0.1	mm
8	Module Size	29.8 (W) x 22.4 (H) x 1.21 (D)	mm ³
9	Diagonal A/A size	1.0	inch
10	Module Weight	1.07 ± 10%	gram

* Panel thickness includes substrate glass, cover glass and UV glue thickness.

5. MAXIMUM RATINGS

ITEM	MIN	MAX	UNIT	Condition	Remark
Supply Voltage (VDD)	-0.3	3.63	V	-40~+85°C	IC maximum rating
Supply Voltage (VCC_C)	8	18	V	-40~+85°C	IC maximum rating
Operating Temp.	-40	70	°C		
Storage Temp	-40	85	°C		
Humidity	-	85	%		
Life Time	21,000	-	Hrs	140cd/m ² , 50% checkerboard	Note (1)
Life Time	25,000		Hrs	120 cd/m ² , 50% checkerboard	Note (2)
Life Time	30,000	-	Hrs	100 cd/m ² , 50% checkerboard	Note (3)

Note:

(A) Under VCC_C = 12V, Ta = 25°C, 50% RH.

(B) Life time is defined the amount of time when the luminance has decayed to less than 50% of the initial measured luminance.

(C) Note (1) 、 Note (2) 、 Note (3) contrast setting are under VDD = 2.8V, set VDD selection(0x3d)=(0x00) and VDD = 1.8V, set VDD selection(0x3d)=(0x01).

(1) Setting of 140 cd/m² :

- Contrast setting : 0x48
- Frame rate : 105Hz
- Duty setting : 1/32

(2) Setting of 120 cd/m² :

- Contrast setting : 0x3d
- Frame rate : 105Hz
- Duty setting : 1/32

(3) Setting of 100 cd/m² :

- Contrast setting : 0x34
- Frame rate : 105Hz
- Duty setting : 1/32

6. ELECTRICAL CHARACTERISTICS

6.1 D.C ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
VDD	Logic Power 1		1.65	1.8	3.5	V
				2.8		
VCC_C	OLED operating voltage		11.5	12	12.5	V
V _{IH}	High Logic Input Level		0.8*VDD	-	VDD	V
V _{IL}	Low Logic Input Level		0	-	0.2*VDD	V
V _{OH}	High Logic Output Level	I _{out} = -100uA	0.9*VDD	-	VDD	V
V _{OL}	Low Logic Output Level	I _{out} = 100uA	0	-	0.1*VDD	V
IIL	Input Leakage Current		-1.0		+1.0	μA
IRVCC	VCC_R Power Regulator Output Voltage	VCC_R = 0.8*VCC_C I _{VCC_R} = 5mA	0.75* VCC_C	0.8* VCC_C	0.85* VCC_C	V

6.2 ELECTRO-OPTICAL CHARACTERISTICS

PANEL ELECTRICAL SPECIFICATIONS

PARAMETER	MIN	TYP.	MAX	UNITS	COMMENTS
Normal mode current		7	8	mA	All pixels on (1)
Standby mode current		2	3	mA	Standby mode 10% pixels on (2)
Normal mode power consumption		84	96	mW	All pixels on (1)
Standby mode power consumption		24	36	mW	Standby mode 10% pixels on (2)
Normal Luminance	100	120		cd/m ²	Display Average
Standby Luminance		30		cd/m ²	Display Average
CIE _x (White)	0.24	0.28	0.32		x, y (CIE 1931)
CIE _y (White)	0.28	0.32	0.36		
Dark Room Contrast	2000:1				
Viewing Angle	160			degree	
Response Time		10		μs	

Note: While VDD is 2.8V, set VDD selection(0x3d)=(0x00) ,VDD is 1.8V, set VDD selection(0x3d)=(0x01) contrast setting is shown below.

(1) Normal mode condition :

- Driving Voltage : 12V
- Contrast setting : 0x3d
- Frame rate : 105Hz
- Duty setting : 1/32

(2) Standby mode condition :

- Driving Voltage : 12V
- Contrast setting : 0x14
- Frame rate : 105Hz
- Duty setting : 1/32

VDD(Analog and digital voltage supply):1.8V 、 2.8V 、 3.3V Setting

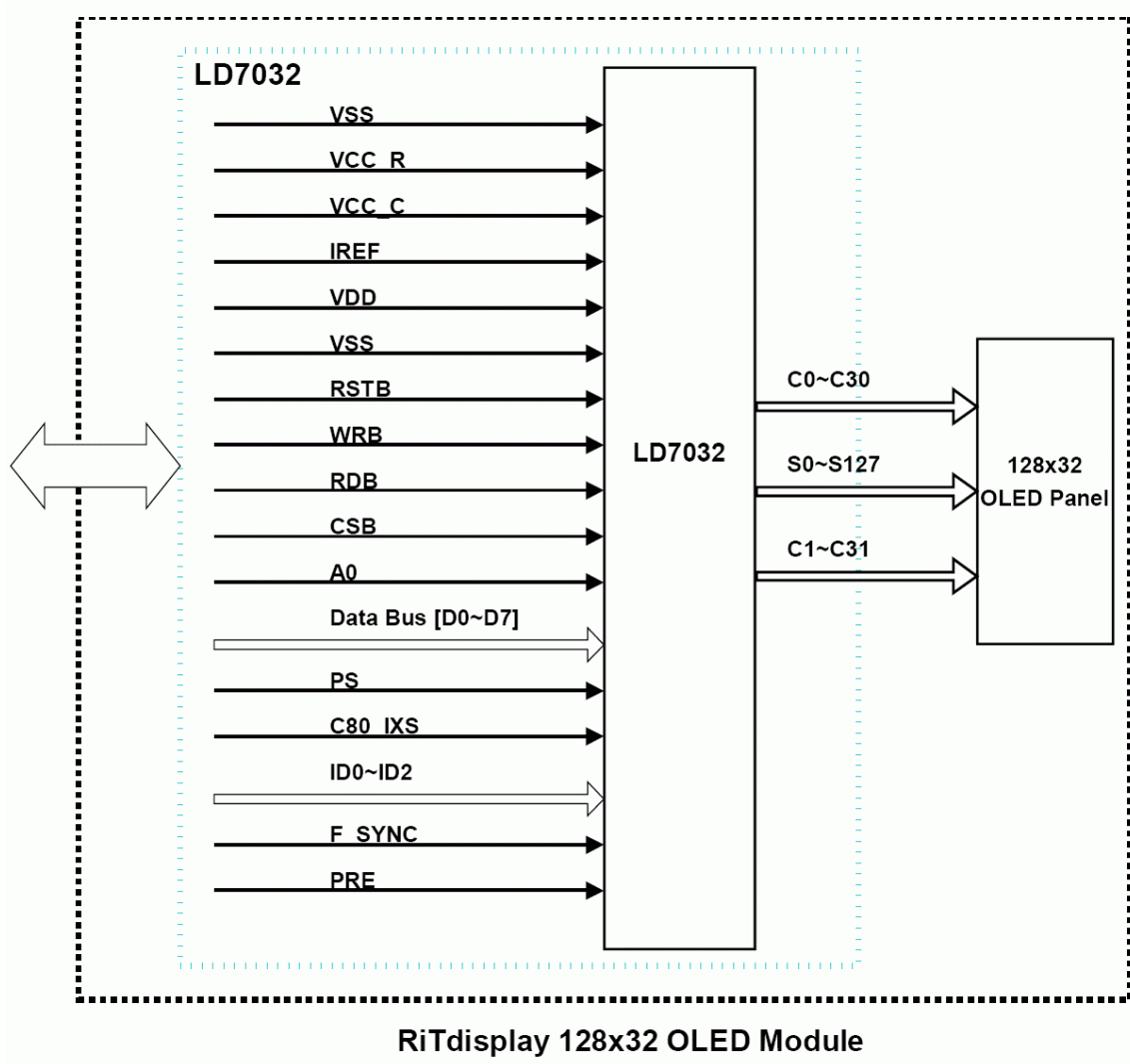
Brightness(cd/m ²)	VDD(V)	Set VDD Selection (0x3d)	Dot Matrix Current Level (0x12)
30(Standby mode)	1.8	0x01	0x14
100(minimum mode)	1.8	0x01	0x34
120(Typical mode)	1.8	0x01	0x3d
140(Maximum mode)	1.8	0x01	0x48

Brightness(cd/m ²)	VDD(V)	Set VDD Selection (0x3d)	Dot Matrix Current Level (0x12)
30(Standby mode)	2.8	0x00	0x14
100(minimum mode)	2.8	0x00	0x34
120(Typical mode)	2.8	0x00	0x3d
140(Maximum mode)	2.8	0x00	0x48

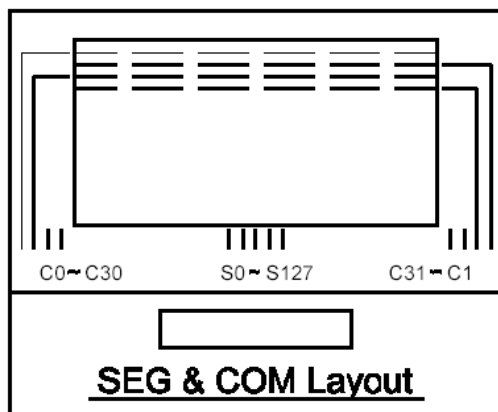
Brightness(cd/m ²)	VDD(V)	Set VDD Selection (0x3d)	Dot Matrix Current Level (0x12)
30(Standby mode)	3.3	0x00	0x11
100(minimum mode)	3.3	0x00	0x2e
120(Typical mode)	3.3	0x00	0x36
140(Maximum mode)	3.3	0x00	0x40

7. INTERFACE

7.1 FUNCTION BLOCK DIAGRAM



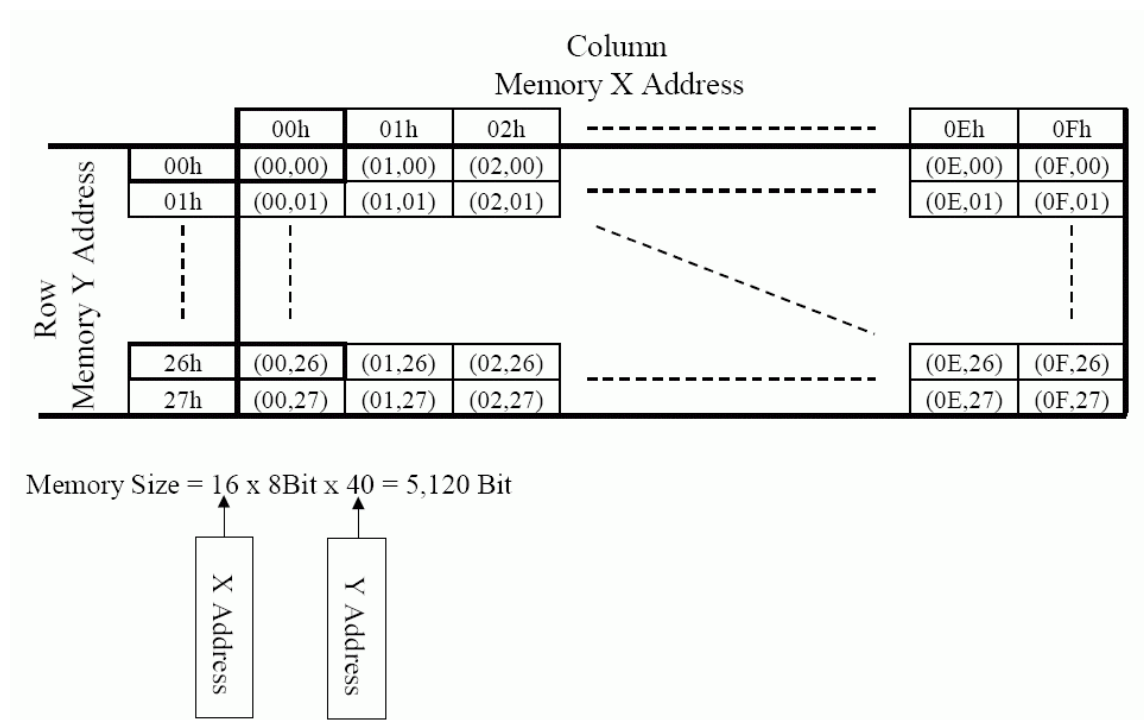
7.2 PANEL LAYOUT DIAGRAM



7.3 PIN ASSIGNMENTS

PIN NO.	PIN NAME	DESCRIPTION
1	VSS	Ground pin.
2	VCC_R	OELD Dot Matrix Power Supply for Row Driver. A 4.7uF capacitor is recommended to connect between VCC_R and GND. If internal row power regulator is disabled, It must be connected to the external high voltage source or VCC_C.
3	VCC_C	OELD Dot Matrix Power Supply for Column VCC_C Driver.
4	IREF	This pin is the dot output current reference pin. A resistor should be connected between this pin and VSS.
5	VDD	Analog and digital voltage supply.
6	VSS	Ground pin.
7	RSTB	Reset (Active Low).
8	WRB	Write (Active Low, 80 Interface). H:Read L:Write (68 Interface).
9	RDB	Read (Active Low, 80 Interface). Enable (68 Interface).
10	CSB	Chip Select (Active Low).
11	A0	Address (L: command, H: Parameter).
12	D7	These are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When I ² C interface mode is selected, D1 will be the I ² C data input (SDA) and D0 will be the I ² C bus clock input (SCL), and D2 ~ D7 should be tied VDD or VSS or floating. When serial interface mode is selected, D1 will be the serial data input (SDIN), D0 will be the serial clock input (SCLK), and D2 ~ D7 should be tied VDD or VSS or floating.
13	D6	
14	D5	
15	D4	
16	D3	
17	D2	
18	D1	
19	D0	
20	PS	
21	C80_IXS	H: 68CPU, I ² C is selected. L: 80CPU, I ² C is not selected.
22	ID2	These pins configure I ² C interface address. Using these pins, I ² C Address can be selected.
23	ID1	
24	ID0	
25	F_SYNC	Frame Sync Signal.
26	PRE	Pre-Charge Voltage.
27	VCC_C	OELD Dot Matrix Power Supply for Column VCC_C Driver.
28	VSS	Ground pin.

7.4 GRAPHIC DISPLAY DATA RAM ADDRESS MAP

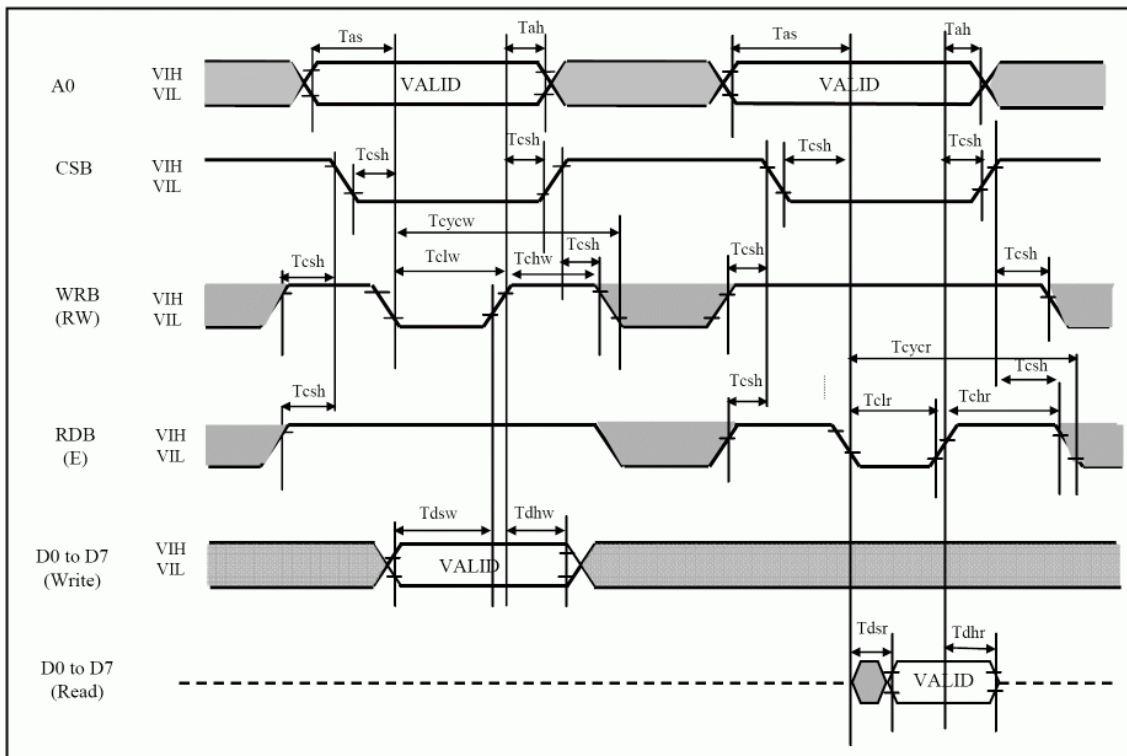


7.5 INTERFACE TIMING CHART

Parallel Interface 1 (Write/Read Timing)

(VSS = 0V, VDD= 2.6V~3.5V, Ta = 25°C)

Parameter	Symbol	Condition		Specification		Units
				MIN	MAX	
Address setup time	Tas	A0		20		ns
Address hold time	Tah	A0		10		
System cycle time	Teyew	WRB	Write	100		
	Teyer	RDB	Read	500		
Write control low pulse width	Tclw	WRB		40		
Write control high pulse width	Tchw			40		
Read control low pulse time	Tclr	RDB		60		
Read control high pulse time	Tchr			80		
Write data setup time	Tdsw	D0 – D7		20		
Write data hold time	Tdhw			10		
Read data setup time (Data Output Access Time)	Tdsr				200	
Read data hold time (Data output disable time)	Tdhr			10		
CSB – WRB, RDB time	Tesh	CSB		10		



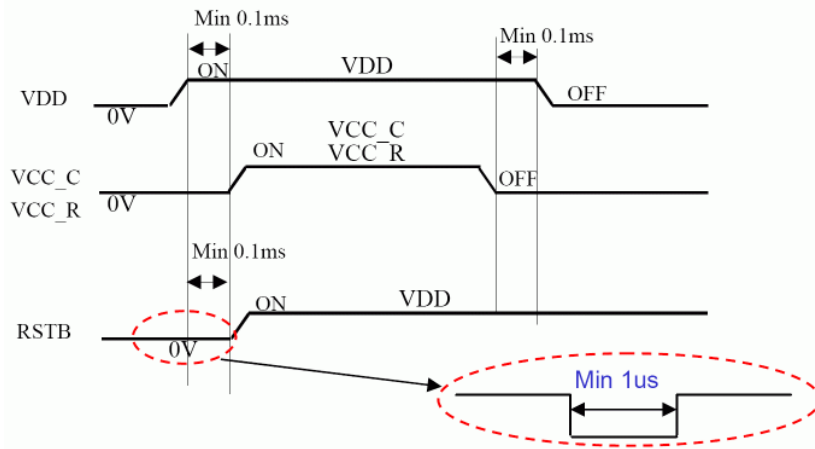
Parallel Interface2 (Write/Read Timing)

(VSS = 0V, VDD= 1.65V~3.5V, Ta = 25°C)

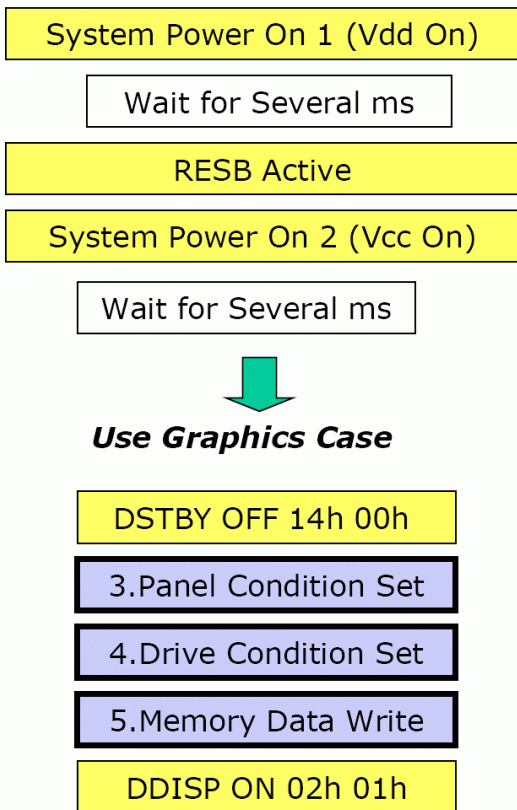
Parameter	Symbol	Condition		Specification		Units
				MIN	MAX	
Address setup time	Tas	A0		60		ns
Address hold time	Tah	A0		30		
System cycle time	Teycw	WRB	Write	300		
	Teyer	RDB	Read	500		
Write control low pulse width	Telw	WRB		120		
Write control high pulse width	Tehw			120		
Read control low pulse time	Tclr	RDB		60		
Read control high pulse time	Tchr			80		
Write data setup time	Tdsw	D0 – D7		60		
Write data hold time	Tdhw			30		
Read data setup time (Data Output Access Time)	Tdsr				200	
Read data hold time (Data output disable time)	Tdhr			10		
CSB – WRB , RDB time	Tesh	CSB		30		

8. POWER ON / OFF SEQUENCE & APPLICATION CIRCUIT

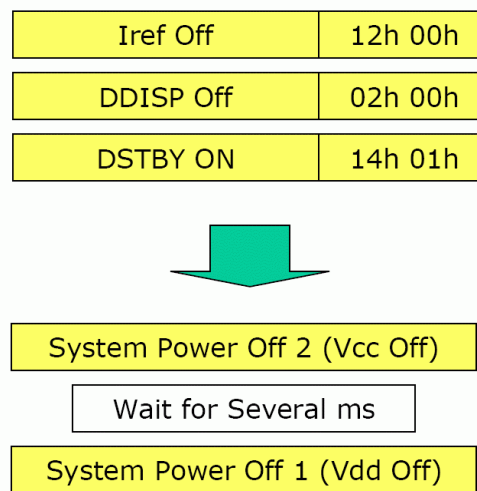
8.1 POWER ON / OFF SEQUENCE



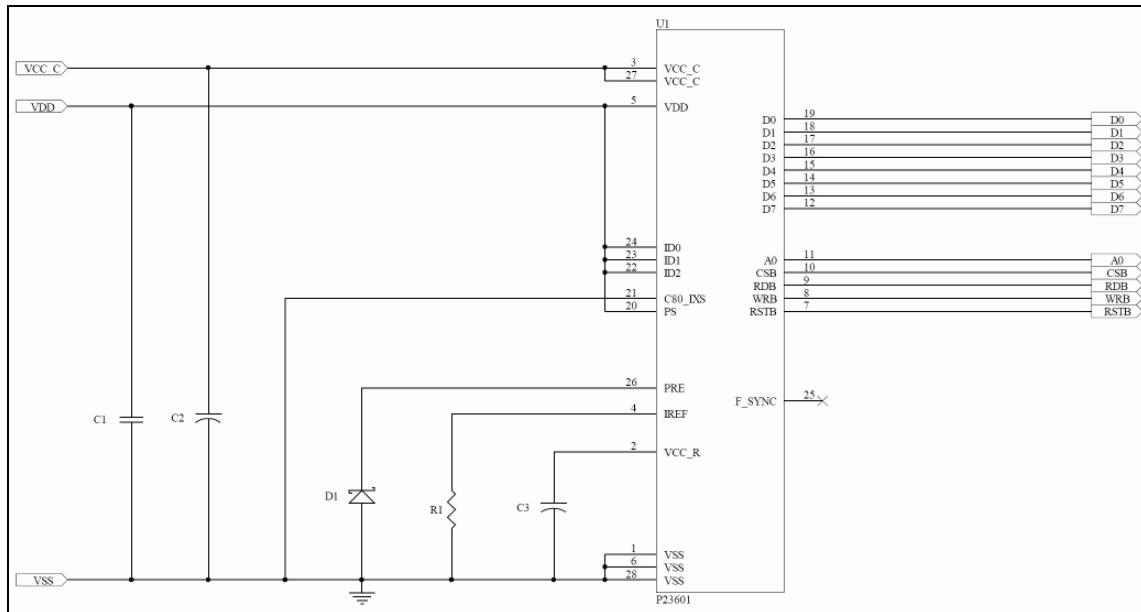
Power On Sequence



Graphics Off Sequence



8.2 APPLICATION CIRCUIT



Recommend components:

C1: 1uF/16V(0603)

C2, C3: 4.7uF/35V (Tantalum type) or VISHAY (572D475X0025A2T)

R1: 68K ohm (0603) 1%

D1: UDZSTE-172.7B or PDZ2.7B (zener diode)

This circuit is for 8080 8bits interface.

8.3 COMMAND TABLE

Refer to LD7032 IC Spec.

9. RELIABILITY TEST CONDITIONS

No.	Items	Specification	Quantity
1	High temp. (Non-operation)	85°C, 240hrs	5
2	High temp. (Operation)	70°C, 120hrs	5
3	Low temp. (Operation)	-40°C, 120hrs	5
4	High temp. / High humidity (Operation)	65°C, 90%RH, 120hrs	5
5	Thermal shock (Non-operation)	-40°C ~85°C (-40°C /30min; transit /3min; 85°C /30min; transit /3min) 1cycle: 66min, 100 cycles	5
6	Vibration	Frequency : 5~50HZ, 0.5G Scan rate : 1 oct/min Time : 2 hrs/axis Test axis : X, Y, Z	1 Carton
7	Drop	Height: 120cm Sequence : 1 angle 、 3 edges and 6 faces Cycles: 1	1 Carton
8	ESD (Non-operation)	Air discharge model, ±8kV, 10 times	5

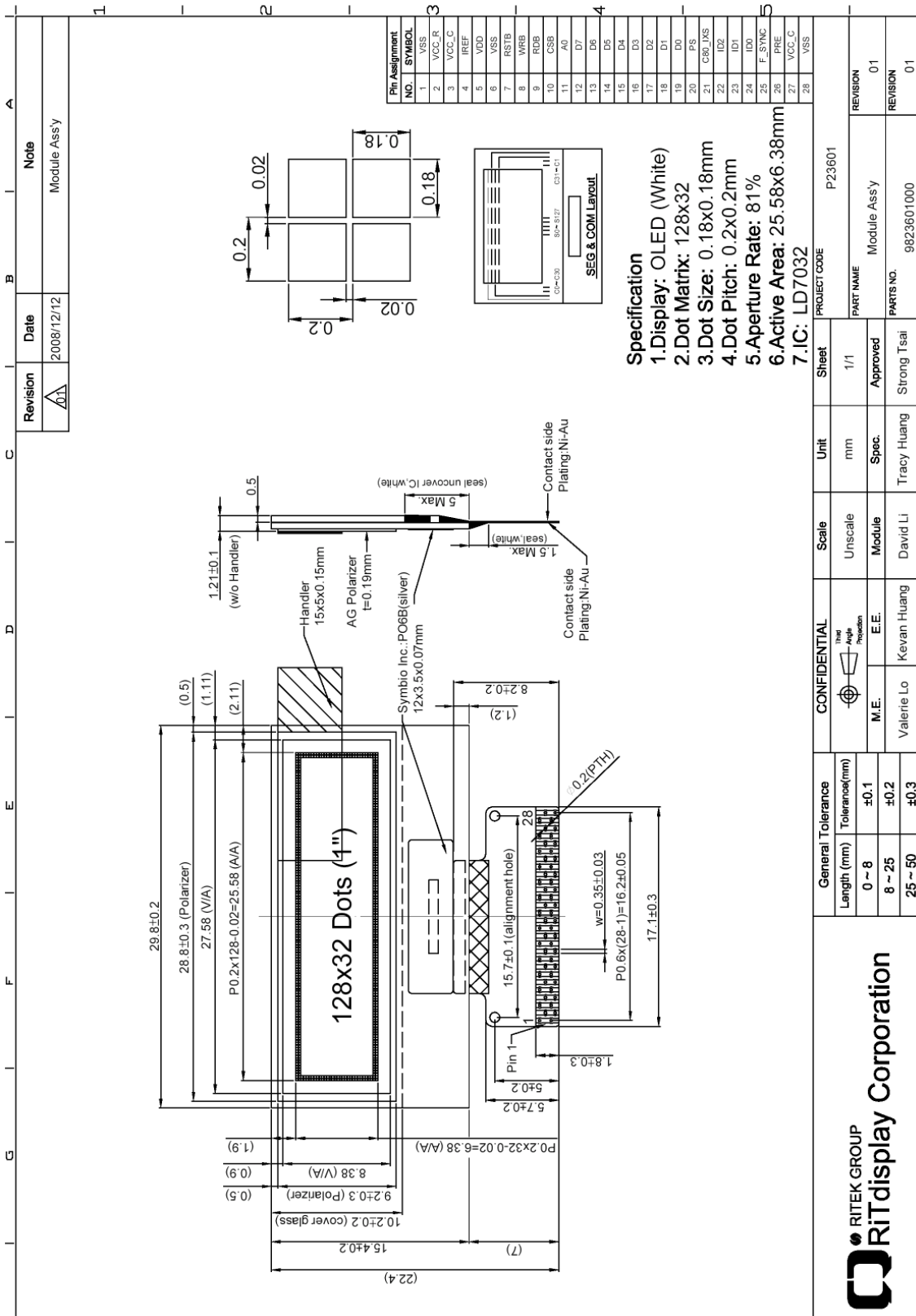
Test and measurement conditions

1. All measurements shall not be started until the specimens attain to temperature stability.
2. All-pixels-on is used as operation test pattern.
3. The degradation of Polarize are ignored for item 1, 4 & 5.

Evaluation criteria

1. The function test is OK.
2. No observable defects.
3. Luminance: > 50% of initial value.
4. Current consumption: within \pm 50% of initial value.

10. EXTERNAL DIMENSION



11. PACKING SPECIFICATION

	Revision ①	Date 2009/04/23	Note Packing Tray Instruction
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① P23601 Module P/N: 9823601000
 Face up, rotate packing
 面朝上, 旋轉放置
 x 1 pcs

② Packing Tray P/N: 3008000237
 330x270x7.8mm, t=0.7mm
 x 1 pcs

③ 5G Silica Gel Desiccants
 5G 矽膠乾燥劑
 P/N: 3010000002
 x 4

④ Vacuum Bag ONY/LDPE
 真空包裝袋, ONY/LDPE
 P/N: 3003000012
 480x285x60mm
 Vacuum Packing-4 sec
 抽真空4秒
 x 21 pcs

⑤ Antistatic Bubble Bag
 抗靜電氣泡袋
 P/N: 3003000016
 440x(350+450)mm
 x 2 pcs

⑥ Pizza Box
 P/N: 3001000005
 345x285x88, B corrugated
 B浪
 x 2 pcs

⑦ 單色 Carton
 P/N: 3000000009
 380x294x175mm
 x 1 pcs

⑧ Label
 標籤
 P/N: 3006000000
 x 2 pcs

⑨ Tape
 封箱膠帶
 P/N: 3208000125

rotate stack
 旋轉堆疊

Item	Part No.	Description	QTY
1	9823601000	P23601 Module Assy	3200
2	3008000237	Tray, 330x270x11mm, .PS, t=0.7mm	42
3	3010000002	5G Silica Gel Desiccants	8
4	3003000012	Vacuum Bag 480x285x60mm	2
5	3003000016	Antistatic Bubble Bag 440x(350+450)mm	2
6	3001000005	Pizza Box 345x285x88, B corrugated	2
7	3000000009	Carton, 385x305x203mm	1
8	3006000000	Label	3
9	3208000125	Tape, W=48mm, L=910cm	

CONFIDENTIAL			PROJECT CODE P23601
Scale 1:3.5	Unit mm	Sheet 1/1	VERSION 01
M.E.	E.E.	Approved	PART NAME Packing Tray Instruction
Turbo Yeh	Kevan Huang	Irene Fan	PARTS NO. 9923601000
David Li	Strong Tsai		

12. APPENDIXES

APPENDIX 1: DEFINITIONS

A. DEFINITION OF CHROMATICITY COORDINATE

The chromaticity coordinate is defined as the coordinate value on the CIE 1931 color chart for R, G, B, W.

B. DEFINITION OF CONTRAST RATIO

The contrast ratio is defined as the following formula:

$$\text{Contrast Ratio} = \frac{\text{Luminance of all pixels on measurement}}{\text{Luminance of all pixels off measurement}}$$

C. DEFINITION OF RESPONSE TIME

The definition of turn-on response time T_r is the time interval between a pixel reaching 10% of steady state luminance and 90% of steady state luminance. The definition of turn-off response time T_f is the time interval between a pixel reaching 90% of steady state luminance and 10% of steady state luminance. It is shown in Figure 2.

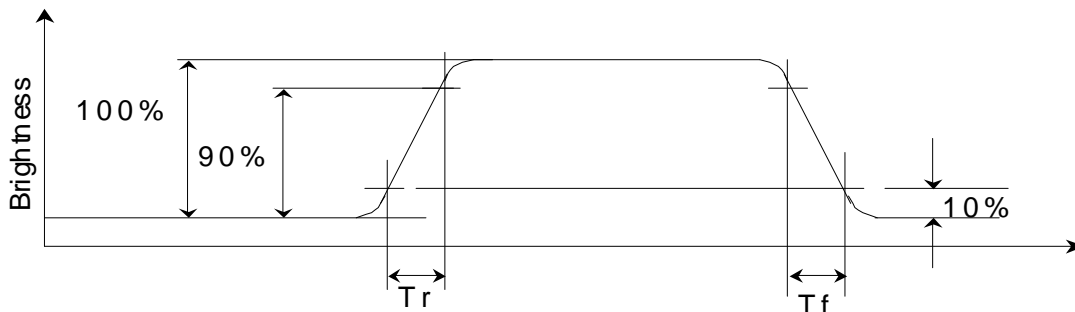


Figure 2: Response time

D. DEFINITION OF VIEWING ANGLE

The viewing angle is defined as Figure 3. Horizontal and vertical (H & V) angles are determined for viewing directions where luminance varies by 50% of the perpendicular value.

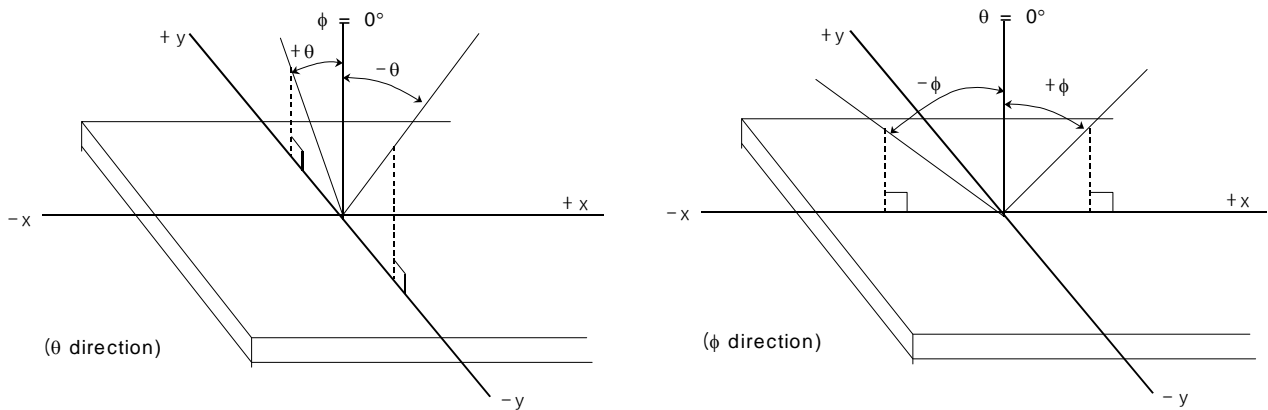
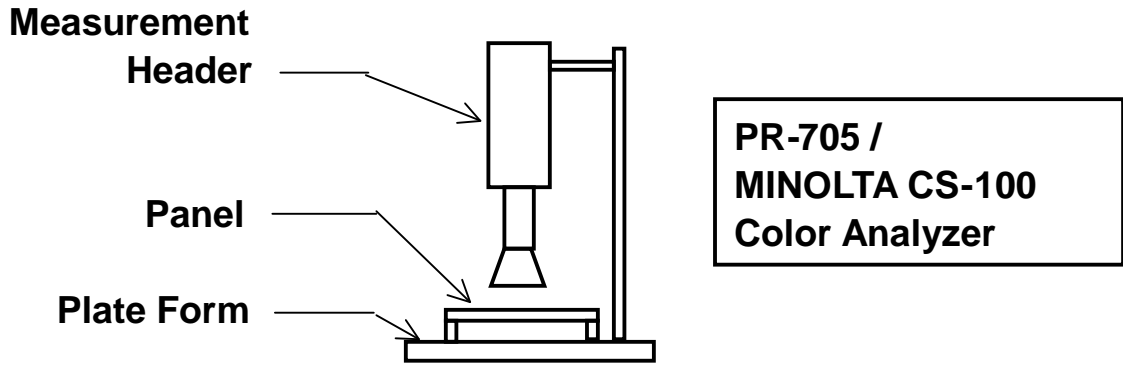


Figure 3: Viewing Angle

APPENDIX 2: MEASUREMENT APPARATUS

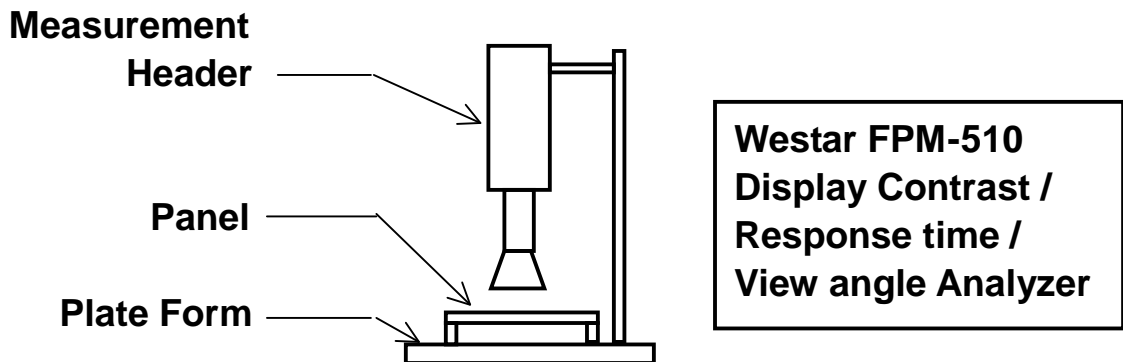
A. LUMINANCE/COLOR COORDINATE

PHOTO RESEARCH PR-705, MINOLTA CS-100

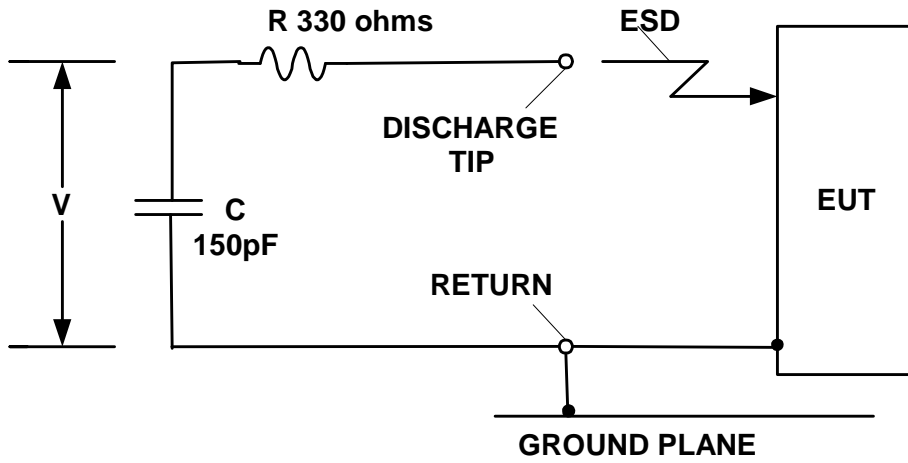


B. CONTRAST / RESPONSE TIME / VIEW ANGLE

WESTAR CORPORATION FPM-510



C. ESD ON AIR DISCHARGE MODE



APPENDIX 3: PRECAUTIONS

A. RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.